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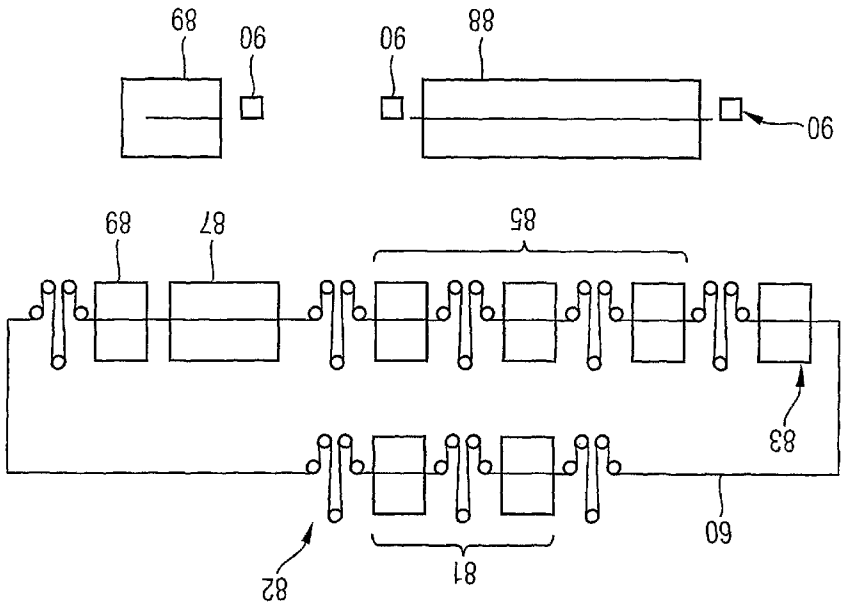
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(54) Title: PACKAGING INTEGRATED CIRCUITS



(57) Abstract: An integrated circuit packaging system having a conveyor 60 for carrying the integrated circuits between some of the processing devices which package the integrated circuits. Leadframe elements 51 comprising die pads 53 and leads 55 are attached to the leadframe element 51 by an attachment apparatus 81. The integrated circuits are attached to the conveyor 60 by a die attachment apparatus 83. Wire bonding is performed by a wire bonding apparatus 85. Moulding is performed by a moulding apparatus 87 to form resin bodies around the integrated circuits. The moulded resin bodies constitute packages. The packages are then removed from the conveyor 60.

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